

Features

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Patented Interlocking Clip Design for High Surge Current Capacity
- High Current Capability and Low Forward Voltage Drop
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **An Automotive-Compliant Part is Available Under Separate Datasheet ([DFLS230LQ](#))**

Mechanical Data

- Case: PowerDI[®] 123
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish – Matte Tin Annealed Over Copper Leadframe. Solderable per MIL-STD-202, Method 208 **(e3)**
- Weight: 0.01 grams (Approximate)



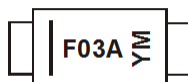
Top View

Ordering Information (Note 4)

Part Number	Case	Packaging
DFLS230L-7	PowerDI123	3000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



F03A = Product Type Marking Code
YM = Date Code Marking
Y = Year (ex: F = 2018)
M = Month (ex: 9 = September)

Date Code Key

Year	2004	~	2012	2013	2014	2015	2016	2017	2018
Code	R	~	Z	A	B	C	D	E	F

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	30	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	21	V
Average Forward Current @ T _T = +121°C	I _{F(AV)}	2.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	33	A

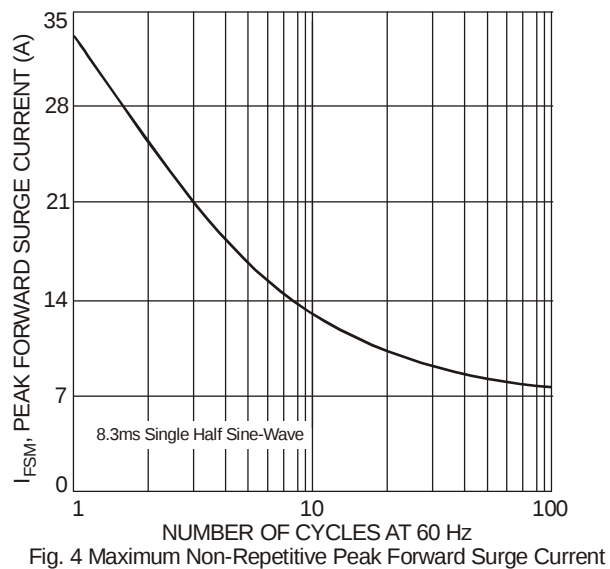
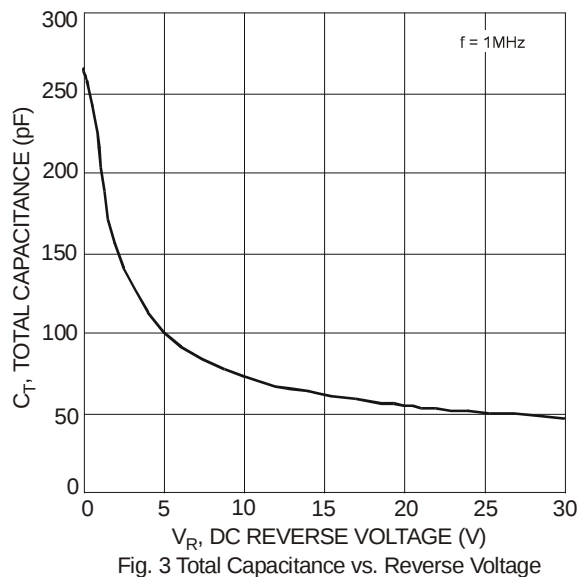
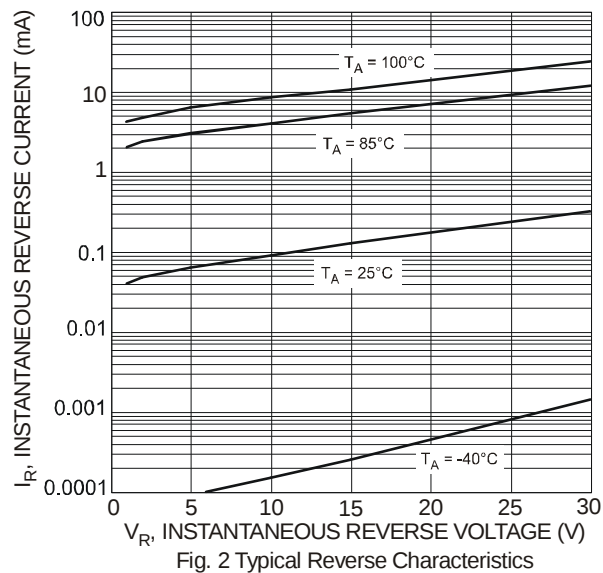
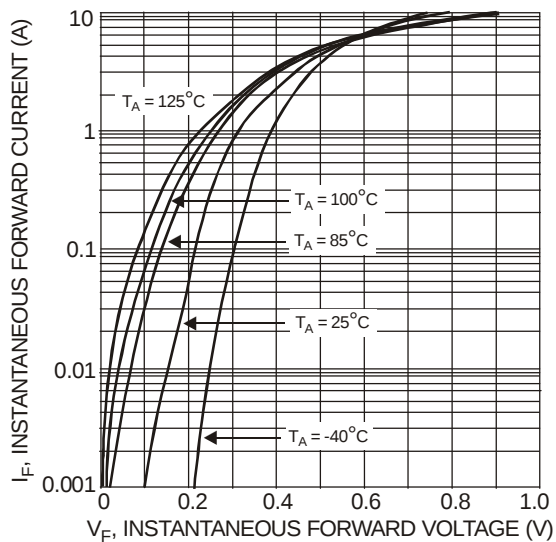
Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P _D	1.67	W
Power Dissipation (Note 6)	P _D	556	mW
Thermal Resistance Junction to Ambient (Note 5)	R _{θJA}	60	°C/W
Thermal Resistance Junction to Ambient (Note 6)	R _{θJA}	180	°C/W
Thermal Resistance Junction to Soldering (Note 7)	R _{θJS}	10	°C/W
Operating Temperature Range	T _J	-40 to +125	°C
Storage Temperature Range	T _{STG}	-40 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 8)	V _{(BR)R}	30	—	—	V	I _R = 1.0mA
Forward Voltage	V _F	—	0.310	—	V	I _F = 1.0A
		—	0.375	0.420		I _F = 2.0A
Leakage Current (Note 8)	I _R	—	0.260	—	mA	V _R = 5V, T _A = +25°C
		—	—	1.0		V _R = 30V, T _A = +25°C
Total Capacitance	C _T	—	76	—	pF	V _R = 10V, f = 1.0MHz

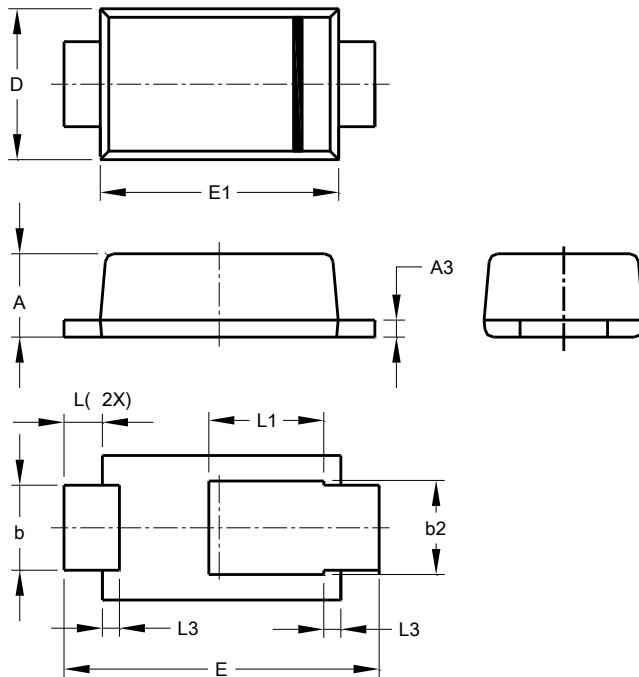
- Notes:
- Part mounted on 2"x2" GETEK board with 1"x1" copper pad, 25% anode, 75% cathode. T_A = +25°C.
 - Part mounted on FR-4 board with recommended pad layout, which can be found on our website at <http://www.diodes.com/package-outlines.html>.
 - Theoretical R_{θJS} calculated from the top center of the die straight down to the PCB/cathode tab solder junction.
 - Short duration pulse test used to minimize self-heating effect.



Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

PowerDI123

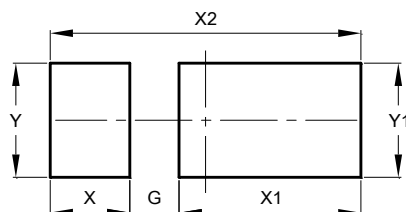


PowerDI123			
Dim	Min	Max	Typ
A	0.93	1.00	0.98
A3	0.15	0.25	0.20
b	0.85	1.25	1.00
b2	1.025	1.125	1.10
D	1.63	1.93	1.78
E	3.50	3.90	3.70
E1	2.60	3.00	2.80
L	0.40	0.50	0.45
L1	1.25	1.40	1.35
L3	0.125	0.275	0.20
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

PowerDI123



Dimensions	Value (in mm)
G	0.65
X	1.05
X1	2.40
X2	4.10
Y	1.50
Y1	1.50

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